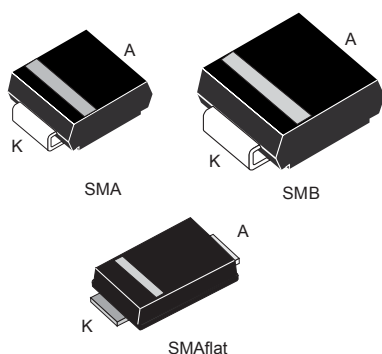


High voltage power Schottky rectifier



Features

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade off between leakage current and forward voltage drop
- Avalanche capability specified
- ECOPACK2[®] halogen-free component

Description

Schottky rectifiers designed for high frequency miniature switched mode power supplies such as adaptors and on board DC/DC converters.

Packaged in SMA, SMAflat, or SMB, this diode is ideal for use in lighting and telecom power applications.

Product status	
STPS1H100	
Product summary	
Symbol	Value
$I_{F(AV)}$	1 A
V_{RRM}	100 V
$T_{j(max.)}$	175 °C
$V_{F(max.)}$	0.62 V

1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			100	V
$I_{F(RMS)}$	Forward rms current			10	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$	SMA	$T_L = 150\text{ °C}$	1	A
		SMB, SMAflat	$T_L = 155\text{ °C}$		
I_{FSM}	Surge non repetitive forward current		$t_p = 10\text{ ms}$ sinusoidal	50	A
P_{ARM}	Repetitive peak avalanche power		$t_p = 10\text{ }\mu\text{s}$, $T_j = 125\text{ °C}$	108	W
T_{stg}	Storage temperature range			-65 to +175	°C
T_j	Maximum operating junction temperature ⁽¹⁾			+175	°C

1. $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal parameters

Symbol	Parameter		Max. value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30	°C/W
		SMB	25	
		SMAflat	25	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		4	μA
		$T_j = 125\text{ °C}$		-	0.2	0.5	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$	-		0.77	V
		$T_j = 125\text{ °C}$		-	0.58	0.62	
		$T_j = 25\text{ °C}$	$I_F = 2\text{ A}$	-		0.86	
		$T_j = 125\text{ °C}$		-	0.65	0.70	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 0.54 \times I_{F(AV)} + 0.08 \times I_{F(RMS)}^2$$

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current

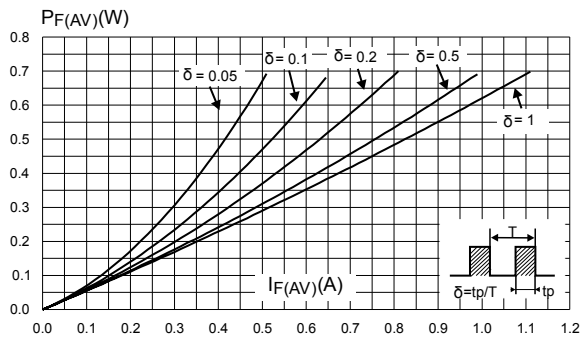


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

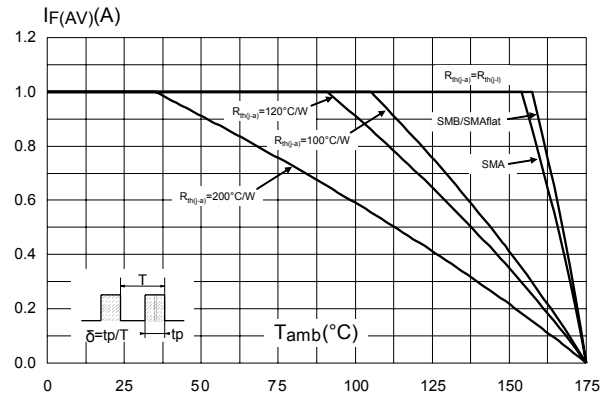


Figure 3. Normalized avalanche power derating versus junction temperature ($T_j = 125^\circ\text{C}$)

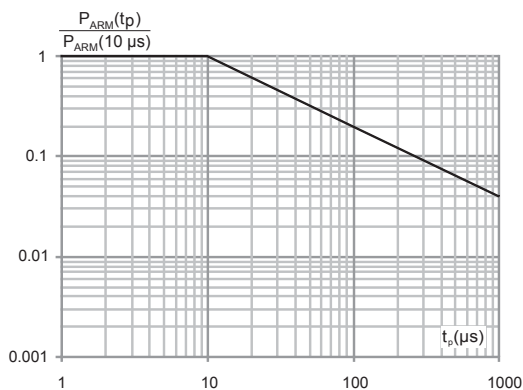


Figure 4. Junction capacitance versus reverse voltage applied (maximum values)

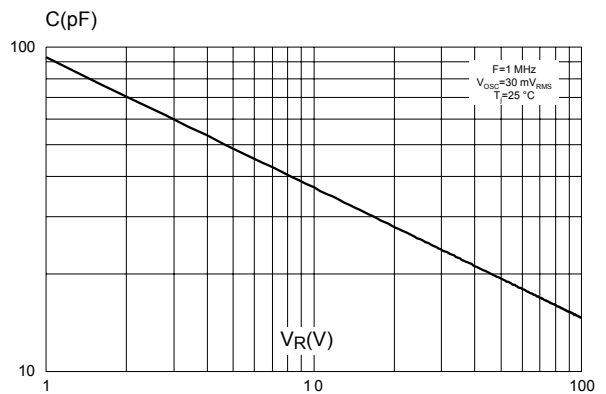


Figure 5. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)

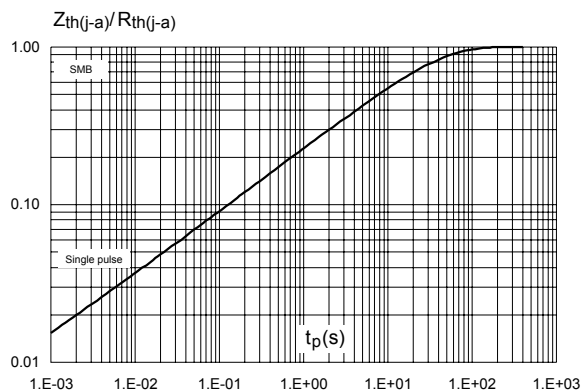


Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)

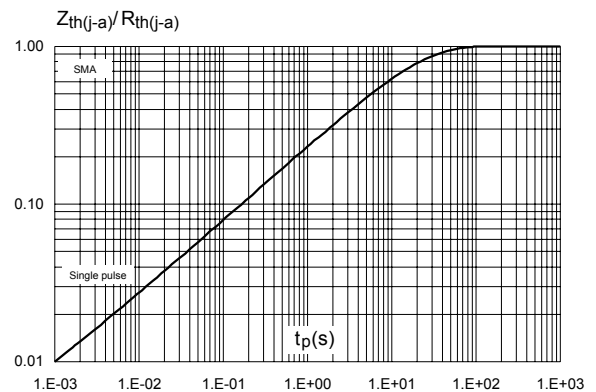
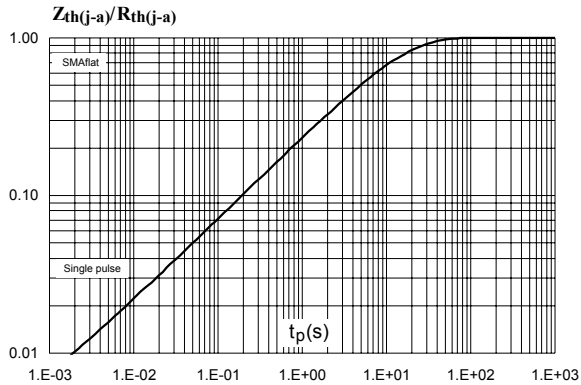
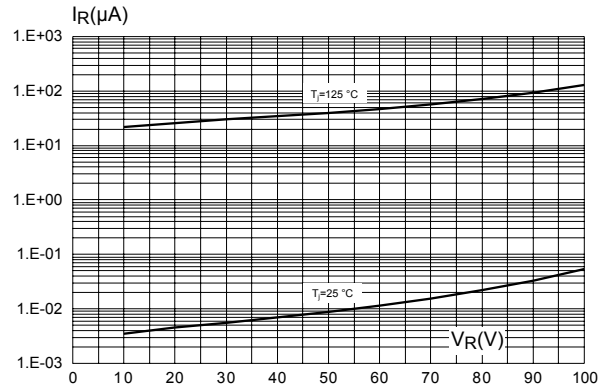
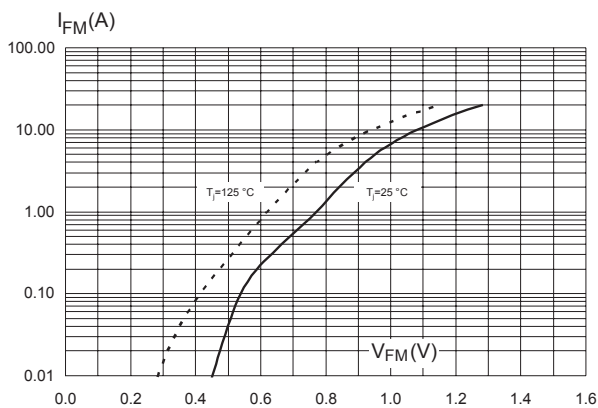
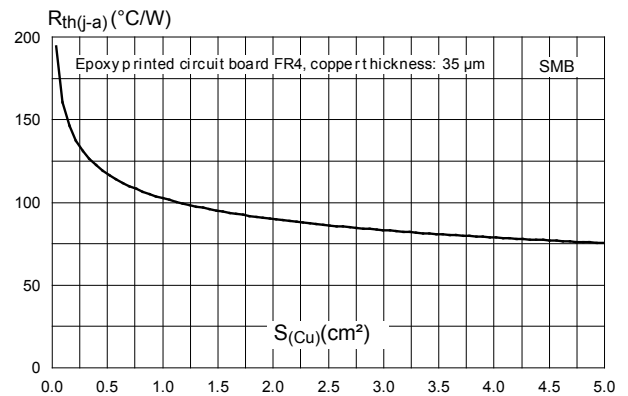
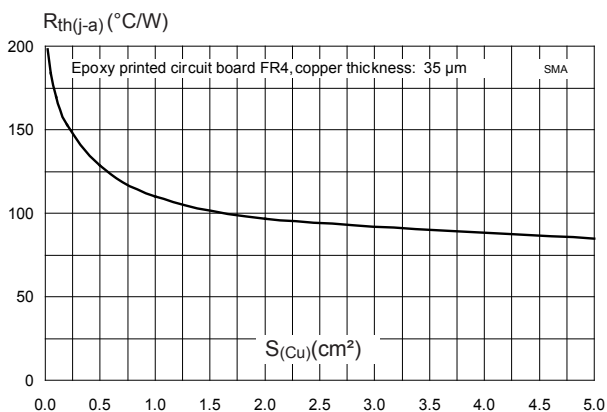
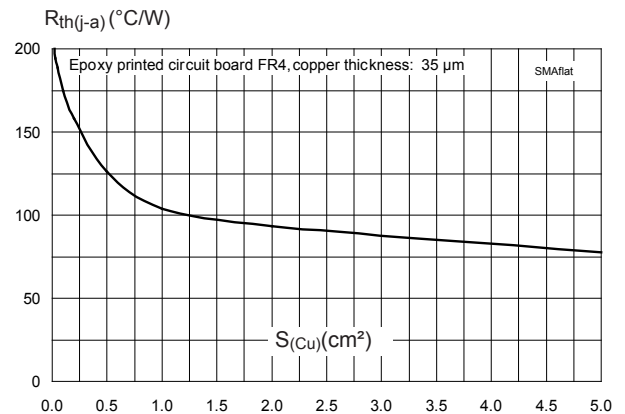


Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration (SMAflat)

Figure 8. Reverse leakage current versus reverse voltage applied (typical values)

Figure 9. Forward voltage drop versus forward current (maximum values)

Figure 10. Thermal resistance junction to ambient versus copper surface under each lead (SMB)

Figure 11. Thermal resistance junction to ambient versus copper surface under each lead (SMA)

Figure 12. Thermal resistance junction to ambient versus copper surface under each lead (SMAflat)


2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 SMB package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 13. SMB package outline

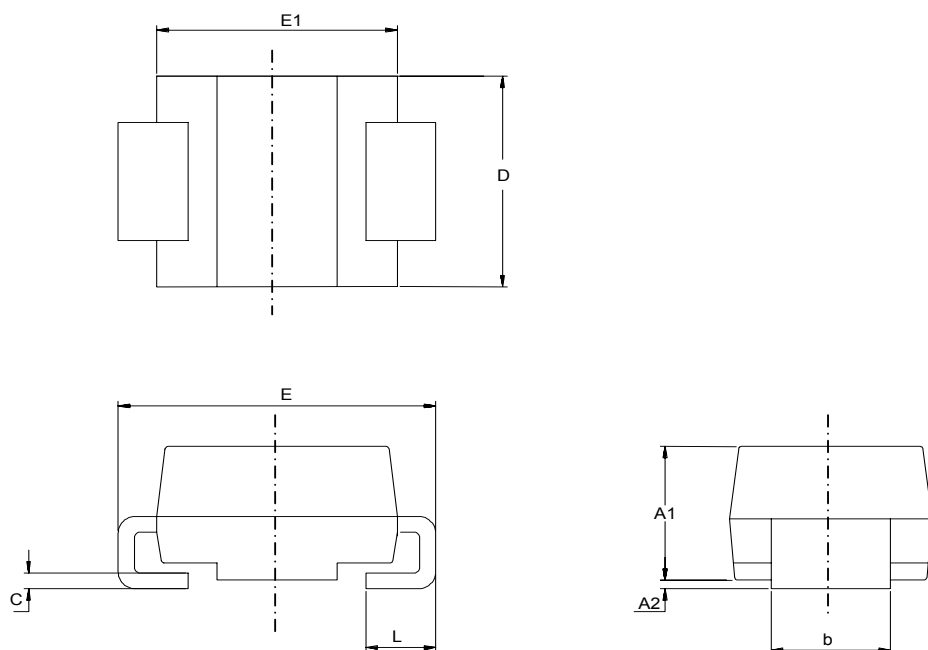
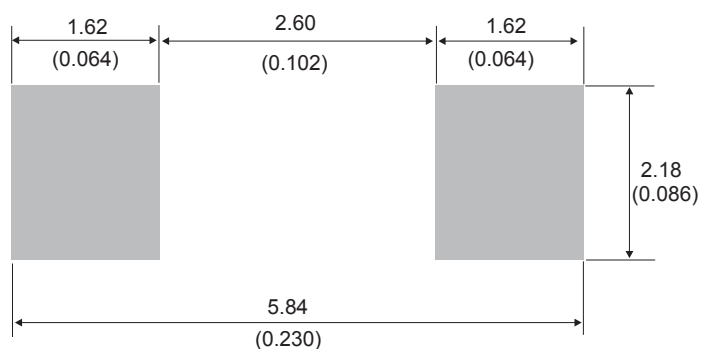


Table 4. SMB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.0748	0.0965
A2	0.05	0.20	0.0020	0.0079
b	1.95	2.20	0.0768	0.0867
c	0.15	0.40	0.0059	0.0157
D	3.30	3.95	0.1299	0.1556
E	5.10	5.60	0.2008	0.2205
E1	4.05	4.60	0.1594	0.1811
L	0.75	1.50	0.0295	0.0591

Figure 14. SMB recommended footprint


2.2 SMA package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 15. SMA package outline

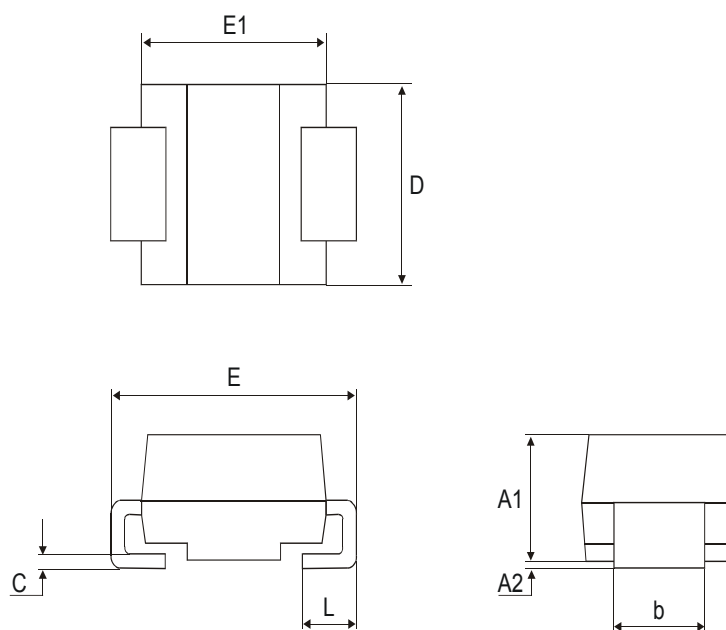
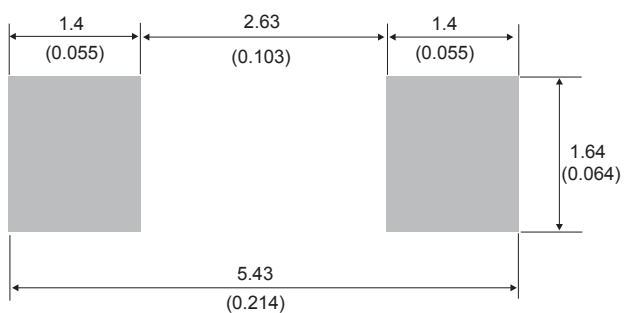


Table 5. SMA package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.097
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059

Figure 16. SMA recommended footprint in mm (inches)



2.3 SMAflat package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 17. SMAflat package outline

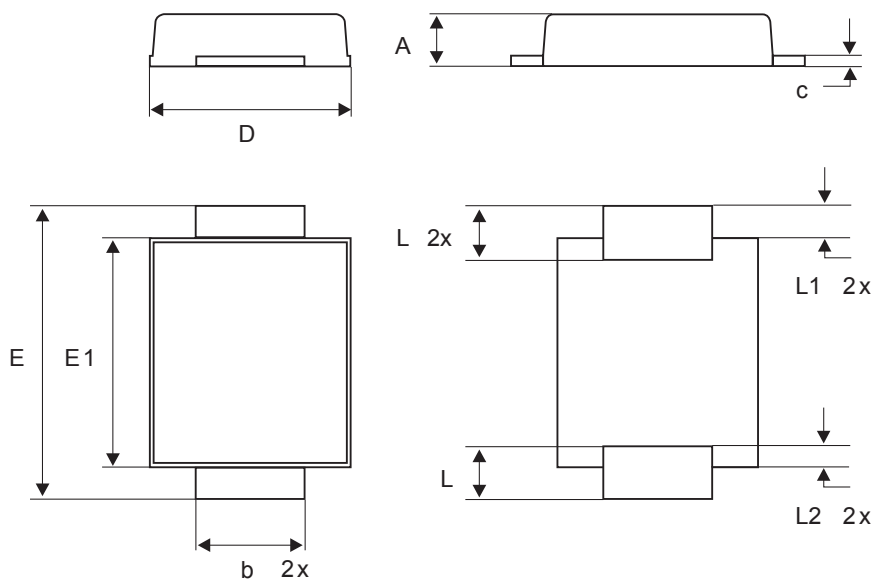
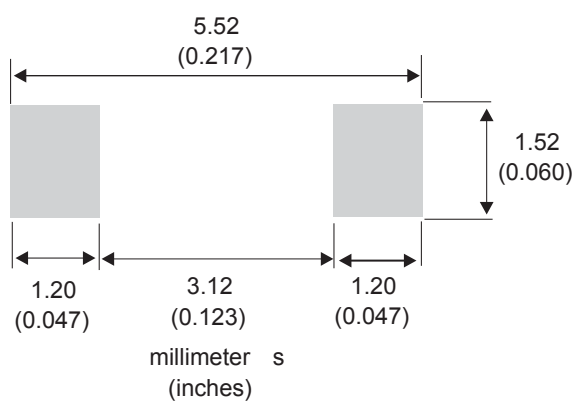


Table 6. SMAflat package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.075		0.097
b	1.25		1.65	0.049		0.065
c	0.15		0.40	0.006		0.016
D	2.25		2.95	0.089		0.116
E	4.80		5.60	0.189		0.220
E1	3.95		4.60	0.156		0.181
L	0.75		1.50	0.030		0.059
L1		0.50			0.020	
L2		0.50			0.020	

Figure 18. SMAflat recommended footprint in mm (inches)



3 Ordering Information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS1H100A	S11	SMA	0.068 g	5000	Tape and reel
STPS1H100U	G11	SMB	0.107 g	2500	Tape and reel
STPS1H100AF	F11	SMAflat	0.035 g	10000	Tape and reel

Revision history

Table 8. Document revision history

Date	Version	Changes
Jul-2003	4A	Last update.
Aug-2004	5	SMA package dimensions update. Reference A1 max changed from 2.70 mm (0.106 inc.) to 2.03 mm (0.080 inc).
18-Sep-2008	6	Reformatted to current standards. Added SMAflat package.
06-Apr-2018	7	Updated Table 1 . Absolute ratings (limiting values at 25 °C, unless otherwise specified), Figure 3 . Normalized avalanche power derating versus junction temperature ($T_j = 125\text{ °C}$). Removed "Normalized avalanche power derating versus junction temperature".

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